



.025" SQ SOCKET HLE SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com/HLE

Insulator Material:
Black Liquid Crystal Polymer



Contact Material:
BeCu



Plating:
Au over 50µ" (1,27µm) Ni

Current Rating:
2.5A @ 80°C ambient

Operating Temp Range:
-55°C to +125°C

Insertion Depth:
(1,78mm) .070" to (3,43mm) .135", pass-through, or (2,59mm) .102" min for bottom entry

Insertion Force:
(Single contact only)
2oz (0,56N) avg

Withdrawal Force:
(Single contact only)
1.6oz (0,44N) avg

RoHS Compliant:
Yes

Processing:

Max Processing Temp:
230°C for 60 seconds, or 260°C for 20 seconds 3x

Lead-Free Solderable:
Yes

SMT Lead Coplanarity:
(0,10mm) .004" max (02-20)
(0,15mm) .006" max (21-50)

HLE	1	NO. PINS PER ROW	02	PLATING OPTION	DV	TAIL OPTION	OTHER OPTION
Mates With: TSW, MTSW, DW, EW, ZW, TLW, TSM, MTLW, HW			-G = 10µ" (0,25µm) Gold		Leave blank for Surface Mount		-BE = Bottom Entry (Requires Surface Mount or -PE)
			-S = 30µ" (0,76µm) Gold on contact, Matte Tin on tail		<p>(Requires -BE for Bottom Entry)</p>		-A = Alignment Pin (4 positions min.) Metal or plastic at Samtec discretion.
02 thru 50							
-PE -TE							
-TE = Through-Hole Top Entry							-LC = Locking Clip (2 positions min.)
-PE = Through-Hole Pass Through Entry							-K = (6,50mm) .256" DIA Polyimide Film Pick & Place Pad (3 positions min.) Not available with -TE or -PE tail option
<p>(Requires -BE for Bottom Entry)</p>							-P = Metal Pick & Place Pad (3 positions min.)
							-TR = Tape & Reel Packaging (29 positions max.)

Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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